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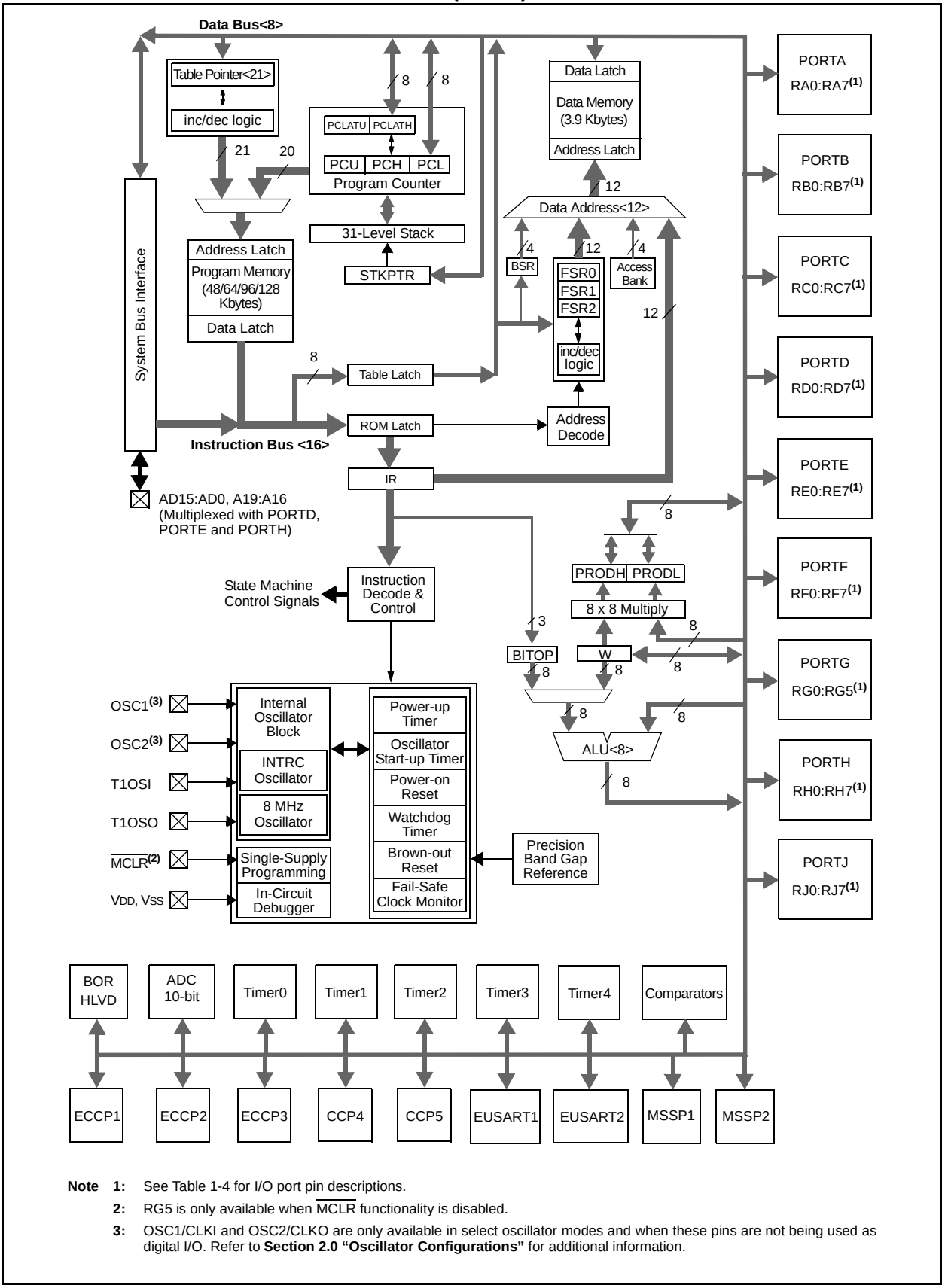
Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	PIC
Core Size	8-Bit
Speed	40MHz
Connectivity	EBI/EMI, I²C, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, HLVD, POR, PWM, WDT
Number of I/O	70
Program Memory Size	96KB (48K x 16)
Program Memory Type	FLASH
EEPROM Size	1K x 8
RAM Size	3.8K x 8
Voltage - Supply (Vcc/Vdd)	2V ~ 5.5V
Data Converters	A/D 16x10b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	80-TQFP
Supplier Device Package	80-TQFP (12x12)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic18lf8627-i-pt

FIGURE 1-2: PIC18F8527/8622/8627/8722 (80-PIN) BLOCK DIAGRAM



Note 1: See Table 1-4 for I/O port pin descriptions.

2: RG5 is only available when $\overline{\text{MCLR}}$ functionality is disabled.

3: OSC1/CLKI and OSC2/CLKO are only available in select oscillator modes and when these pins are not being used as digital I/O. Refer to **Section 2.0 "Oscillator Configurations"** for additional information.

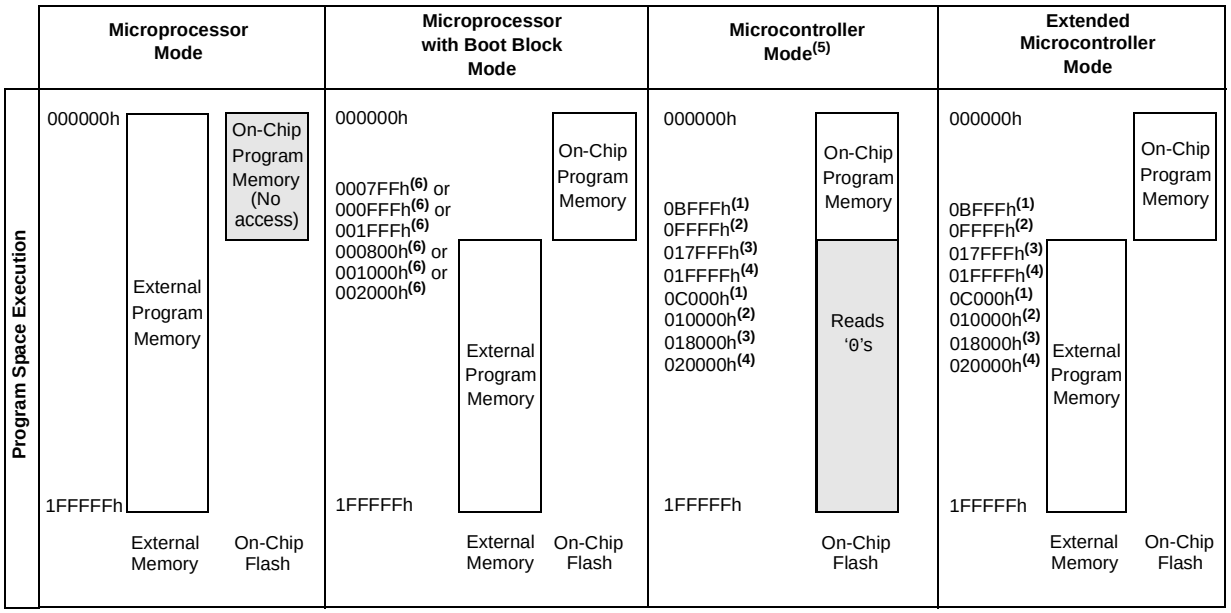
TABLE 1-3: PIC18F6527/6622/6627/6722 PINOUT I/O DESCRIPTIONS (CONTINUED)

Pin Name	Pin Number	Pin Type	Buffer Type	Description
	TQFP			
				PORTG is a bidirectional I/O port.
RG0/ECCP3/P3A	3			
RG0		I/O	ST	Digital I/O.
ECCP3		I/O	ST	Enhanced Capture 3 input/Compare 3 output/ PWM 3 output.
P3A		O	—	ECCP3 PWM output A.
RG1/TX2/CK2	4			
RG1		I/O	ST	Digital I/O.
TX2		O	—	EUSART2 asynchronous transmit.
CK2		I/O	ST	EUSART2 synchronous clock (see related RX2/DT2).
RG2/RX2/DT2	5			
RG2		I/O	ST	Digital I/O.
RX2		I	ST	EUSART2 asynchronous receive.
DT2		I/O	ST	EUSART2 synchronous data (see related TX2/CK2).
RG3/CCP4/P3D	6			
RG3		I/O	ST	Digital I/O.
CCP4		I/O	ST	Capture 4 input/Compare 4 output/PWM 4 output.
P3D		O	—	ECCP3 PWM output D.
RG4/CCP5/P1D	8			
RG4		I/O	ST	Digital I/O.
CCP5		I/O	ST	Capture 5 input/Compare 5 output/PWM 5 output.
P1D		O	—	ECCP1 PWM output D.
RG5				See RG5/$\overline{MCLR}$/V_{PP} pin.
V_{SS}	9, 25, 41, 56	P	—	Ground reference for logic and I/O pins.
V_{DD}	10, 26, 38, 57	P	—	Positive supply for logic and I/O pins.
AV_{SS}	20	P	—	Ground reference for analog modules.
AV_{DD}	19	P	—	Positive supply for analog modules.

Legend: TTL = TTL compatible input CMOS = CMOS compatible input or output
ST = Schmitt Trigger input with CMOS levels Analog = Analog input
I = Input O = Output
P = Power I^2C™ = I^2C/SMBus input buffer

Note 1: Default assignment for ECCP2 when Configuration bit, CCP2MX, is set.
2: Alternate assignment for ECCP2 when Configuration bit, CCP2MX, is cleared.

FIGURE 5-2: MEMORY MAPS FOR PIC18F8722 FAMILY PROGRAM MEMORY MODES



Note 1: PIC18F6527 and PIC18F8527.
2: PIC18F6622 and PIC18F8622.
3: PIC18F6627 and PIC18F8627.
4: PIC18F6722 and PIC18F8722.
5: This is the **only** mode available on PIC18F6527/6622/6627/6722 devices.
6: Boot block size is determined by the BBSIZ<1:0> bits in CONFIG4L.

6.5 Writing to Flash Program Memory

The minimum programming block is 32 words or 64 bytes. Word or byte programming is not supported.

Table writes are used internally to load the holding registers needed to program the Flash memory. There are 64 holding registers used by the table writes for programming.

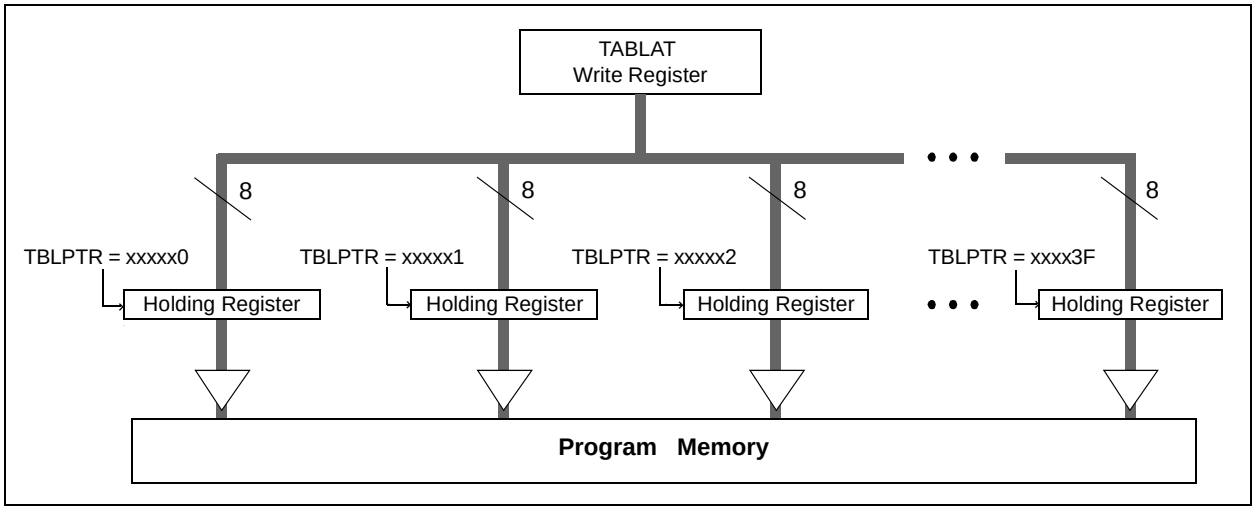
Since the Table Latch (TABLAT) is only a single byte, the TBLWT instruction may need to be executed 64 times for each programming operation. All of the table write operations will essentially be short writes because only the holding registers are written. At the end of updating the 64 holding registers, the EECON1 register must be written to in order to start the programming operation with a long write.

The long write is necessary for programming the internal Flash. Instruction execution is halted while in a long write cycle. The long write will be terminated by the internal programming timer.

The EEPROM on-chip timer controls the write time. The write/erase voltages are generated by an on-chip charge pump, rated to operate over the voltage range of the device.

Note:	The default value of the holding registers on device Resets and after write operations is FFh. A write of FFh to a holding register does not modify that byte. This means that individual bytes of program memory may be modified, provided that the change does not attempt to change any bit from a '0' to a '1'. When modifying individual bytes, it is not necessary to load all 64 holding registers before executing a write operation.

FIGURE 6-5: TABLE WRITES TO FLASH PROGRAM MEMORY



6.5.1 FLASH PROGRAM MEMORY WRITE SEQUENCE

The sequence of events for programming an internal program memory location should be:

1. Read 64 bytes into RAM.
2. Update data values in RAM as necessary.
3. Load Table Pointer register with address being erased.
4. Execute the row erase procedure.
5. Load Table Pointer register with address of first byte being written.
6. Write the 64 bytes into the holding registers with auto-increment.
7. Set the EECON1 register for the write operation:
   - set EEPGD bit to point to program memory;
   - clear the CFGS bit to access program memory;
   - set WREN to enable byte writes.
8. Disable interrupts.
9. Write 55h to EECON2.
10. Write 0AAh to EECON2.
11. Set the WR bit. This will begin the write cycle.
12. The CPU will stall for duration of the write for TIW (see parameter D133A).
13. Re-enable interrupts.
14. Verify the memory (table read).

An example of the required code is shown in Example 6-3 on the following page.

Note:	Before setting the WR bit, the Table Pointer address needs to be within the intended address range of the 64 bytes in the holding register.

Example 9-3 shows the sequence to do a 16 x 16 unsigned multiplication. Equation 9-1 shows the algorithm that is used. The 32-bit result is stored in four registers (RES3:RES0).

EQUATION 9-1: 16 x 16 UNSIGNED MULTIPLICATION ALGORITHM

$$
\begin{aligned}
RES3:RES0 &= ARG1H:ARG1L \bullet ARG2H:ARG2L \\
&= (ARG1H \bullet ARG2H \bullet 2^{16}) + \\
&\quad (ARG1H \bullet ARG2L \bullet 2^{8}) + \\
&\quad (ARG1L \bullet ARG2H \bullet 2^{8}) + \\
&\quad (ARG1L \bullet ARG2L)
\end{aligned}
$$

EXAMPLE 9-3: 16 x 16 UNSIGNED MULTIPLY ROUTINE

```
    MOVF    ARG1L, W
    MULWF   ARG2L           ; ARG1L * ARG2L->
                            ; PRODH:PRODL
    MOVFF   PRODH, RES1     ;
    MOVFF   PRODL, RES0     ;
;
    MOVF    ARG1H, W
    MULWF   ARG2H           ; ARG1H * ARG2H->
                            ; PRODH:PRODL
    MOVFF   PRODH, RES3     ;
    MOVFF   PRODL, RES2     ;
;
    MOVF    ARG1L, W
    MULWF   ARG2H           ; ARG1L * ARG2H->
                            ; PRODH:PRODL
    MOVF    PRODL, W        ;
    ADDWF   RES1, F         ; Add cross
    MOVF    PRODH, W        ; products
    ADDWFC  RES2, F         ;
    CLRF    WREG            ;
    ADDWFC  RES3, F         ;
;
    MOVF    ARG1H, W        ;
    MULWF   ARG2L           ; ARG1H * ARG2L->
                            ; PRODH:PRODL
    MOVF    PRODL, W        ;
    ADDWF   RES1, F         ; Add cross
    MOVF    PRODH, W        ; products
    ADDWFC  RES2, F         ;
    CLRF    WREG            ;
    ADDWFC  RES3, F         ;
```

Example 9-4 shows the sequence to do a 16 x 16 signed multiply. Equation 9-2 shows the algorithm used. The 32-bit result is stored in four registers (RES<3:0>). To account for the sign bits of the arguments, the MSb for each argument pair is tested and the appropriate subtractions are done.

EQUATION 9-2: 16 x 16 SIGNED MULTIPLICATION ALGORITHM

$$
\begin{aligned}
RES3:RES0 &= ARG1H:ARG1L \bullet ARG2H:ARG2L \\
&= (ARG1H \bullet ARG2H \bullet 2^{16}) + \\
&\quad (ARG1H \bullet ARG2L \bullet 2^{8}) + \\
&\quad (ARG1L \bullet ARG2H \bullet 2^{8}) + \\
&\quad (ARG1L \bullet ARG2L) + \\
&\quad (-1 \bullet ARG2H\langle 7\rangle \bullet ARG1H:ARG1L \bullet 2^{16}) + \\
&\quad (-1 \bullet ARG1H\langle 7\rangle \bullet ARG2H:ARG2L \bullet 2^{16})
\end{aligned}
$$

EXAMPLE 9-4: 16 x 16 SIGNED MULTIPLY ROUTINE

```
    MOVF    ARG1L, W
    MULWF   ARG2L           ; ARG1L * ARG2L ->
                            ; PRODH:PRODL
    MOVFF   PRODH, RES1     ;
    MOVFF   PRODL, RES0     ;
;
    MOVF    ARG1H, W
    MULWF   ARG2H           ; ARG1H * ARG2H ->
                            ; PRODH:PRODL
    MOVFF   PRODH, RES3     ;
    MOVFF   PRODL, RES2     ;
;
    MOVF    ARG1L, W
    MULWF   ARG2H           ; ARG1L * ARG2H ->
                            ; PRODH:PRODL
    MOVF    PRODL, W        ;
    ADDWF   RES1, F         ; Add cross
    MOVF    PRODH, W        ; products
    ADDWFC  RES2, F         ;
    CLRF    WREG            ;
    ADDWFC  RES3, F         ;
;
    MOVF    ARG1H, W        ;
    MULWF   ARG2L           ; ARG1H * ARG2L ->
                            ; PRODH:PRODL
    MOVF    PRODL, W        ;
    ADDWF   RES1, F         ; Add cross
    MOVF    PRODH, W        ; products
    ADDWFC  RES2, F         ;
    CLRF    WREG            ;
    ADDWFC  RES3, F         ;
;
    BTFSS   ARG2H, 7        ; ARG2H:ARG2L neg?
    BRA     SIGN_ARG1       ; no, check ARG1
    MOVF    ARG1L, W        ;
    SUBWF   RES2            ;
    MOVF    ARG1H, W        ;
    SUBWFB  RES3
;
SIGN_ARG1
    BTFSS   ARG1H, 7        ; ARG1H:ARG1L neg?
    BRA     CONT_CODE       ; no, done
    MOVF    ARG2L, W        ;
    SUBWF   RES2            ;
    MOVF    ARG2H, W        ;
    SUBWFB  RES3
;
CONT_CODE
   :
```

15.2 Timer3 16-bit Read/Write Mode

Timer3 can be configured for 16-bit reads and writes (see Figure 15-2). When the RD16 control bit (T3CON<7>) is set, the address for TMR3H is mapped to a buffer register for the high byte of Timer3. A read from TMR3L will load the contents of the high byte of Timer3 into the Timer3 High Byte Buffer register. This provides the user with the ability to accurately read all 16 bits of Timer3 without having to determine whether a read of the high byte, followed by a read of the low byte, has become invalid due to a rollover between reads.

A write to the high byte of Timer3 must also take place through the TMR3H Buffer register. The Timer3 high byte is updated with the contents of TMR3H when a write occurs to TMR3L. This allows a user to write all 16 bits to both the high and low bytes of Timer3 at once.

The high byte of Timer3 is not directly readable or writable in this mode. All reads and writes must take place through the Timer3 High Byte Buffer register.

Writes to TMR3H do not clear the Timer3 prescaler. The prescaler is only cleared on writes to TMR3L.

15.3 Using the Timer1 Oscillator as the Timer3 Clock Source

The Timer1 internal oscillator may be used as the clock source for Timer3. The Timer1 oscillator is enabled by setting the T1OSCEN (T1CON<3>) bit. To use it as the Timer3 clock source, the TMR3CS bit must also be set. As previously noted, this also configures Timer3 to increment on every rising edge of the oscillator source.

The Timer1 oscillator is described in **Section 13.0 "Timer1 Module"**.

15.4 Timer3 Interrupt

The TMR3 register pair (TMR3H:TMR3L) increments from 0000h to FFFFh and overflows to 0000h. The Timer3 interrupt, if enabled, is generated on overflow and is latched in interrupt flag bit, TMR3IF (PIR2<1>). This interrupt can be enabled or disabled by setting or clearing the Timer3 Interrupt Enable bit, TMR3IE (PIE2<1>).

15.5 Resetting Timer3 Using the CCP Special Event Trigger

If any of the CCP modules are configured to use Timer3 and to generate a Special Event Trigger in Compare mode (CCPxM<3:0> = 1011), this signal will reset Timer3. ECCP2 can also start an A/D conversion if the A/D module is enabled (see **Section 17.3.4 "Special Event Trigger"** for more information).

The module must be configured as either a timer or synchronous counter to take advantage of this feature. When used this way, the CCPRxH:CCPRxL register pair effectively becomes a period register for Timer3.

If Timer3 is running in Asynchronous Counter mode, the Reset operation may not work.

In the event that a write to Timer3 coincides with a Special Event Trigger from a CCP module, the write will take precedence.

Note:	The Special Event Triggers from the CCPx module will not set the TMR3IF interrupt flag bit (PIR2<1>).

TABLE 15-1: REGISTERS ASSOCIATED WITH TIMER3 AS A TIMER/COUNTER

Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Reset Values on page
INTCON	GIE/GIEH	PEIE/GIEL	TMR0IE	INT0IE	RBIE	TMR0IF	INT0IF	RBIF	57
PIR2	OSCFIF	CMIF	—	EEIF	BCL1IF	HLVDIF	TMR3IF	CCP2IF	60
PIE2	OSCFIE	CMIE	—	EEIE	BCL1IE	HLVDIE	TMR3IE	CCP2IE	60
IPR2	OSCFIP	CMIP	—	EEIP	BCL1IP	HLVDIP	TMR3IP	CCP2IP	60
TMR3L	Timer3 Register Low Byte								59
TMR3H	Timer3 Register High Byte								59
T1CON	RD16	T1RUN	T1CKPS1	T1CKPS0	T1OSCEN	$\overline{\text{T1SYNC}}$	TMR1CS	TMR1ON	58
T3CON	RD16	T3CCP2	T3CKPS1	T3CKPS0	T3CCP1	$\overline{\text{T3SYNC}}$	TMR3CS	TMR3ON	59

Legend: — = unimplemented, read as '0'. Shaded cells are not used by the Timer3 module.

16.2 Timer4 Interrupt

The Timer4 module has an 8-bit Period register, PR4, which is both readable and writable. Timer4 increments from 00h until it matches PR4 and then resets to 00h on the next increment cycle. The PR4 register is initialized to FFh upon Reset.

16.3 Output of TMR4

The output of TMR4 (before the postscaler) is used only as a PWM time base for the CCP modules. It is not used as a baud rate clock for the MSSP, as is the Timer2 output.

FIGURE 16-1: TIMER4 BLOCK DIAGRAM

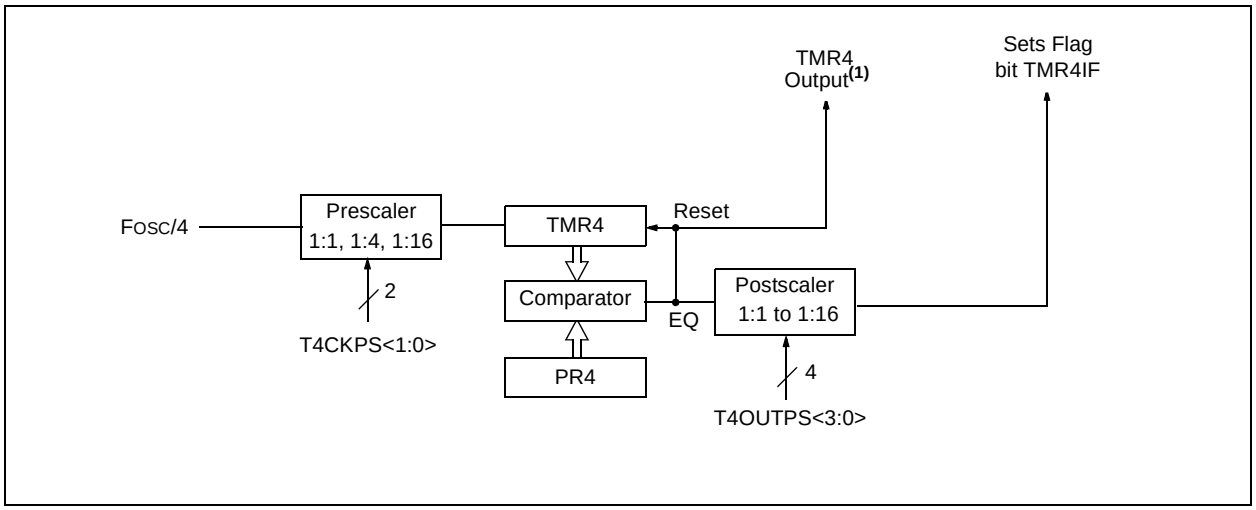
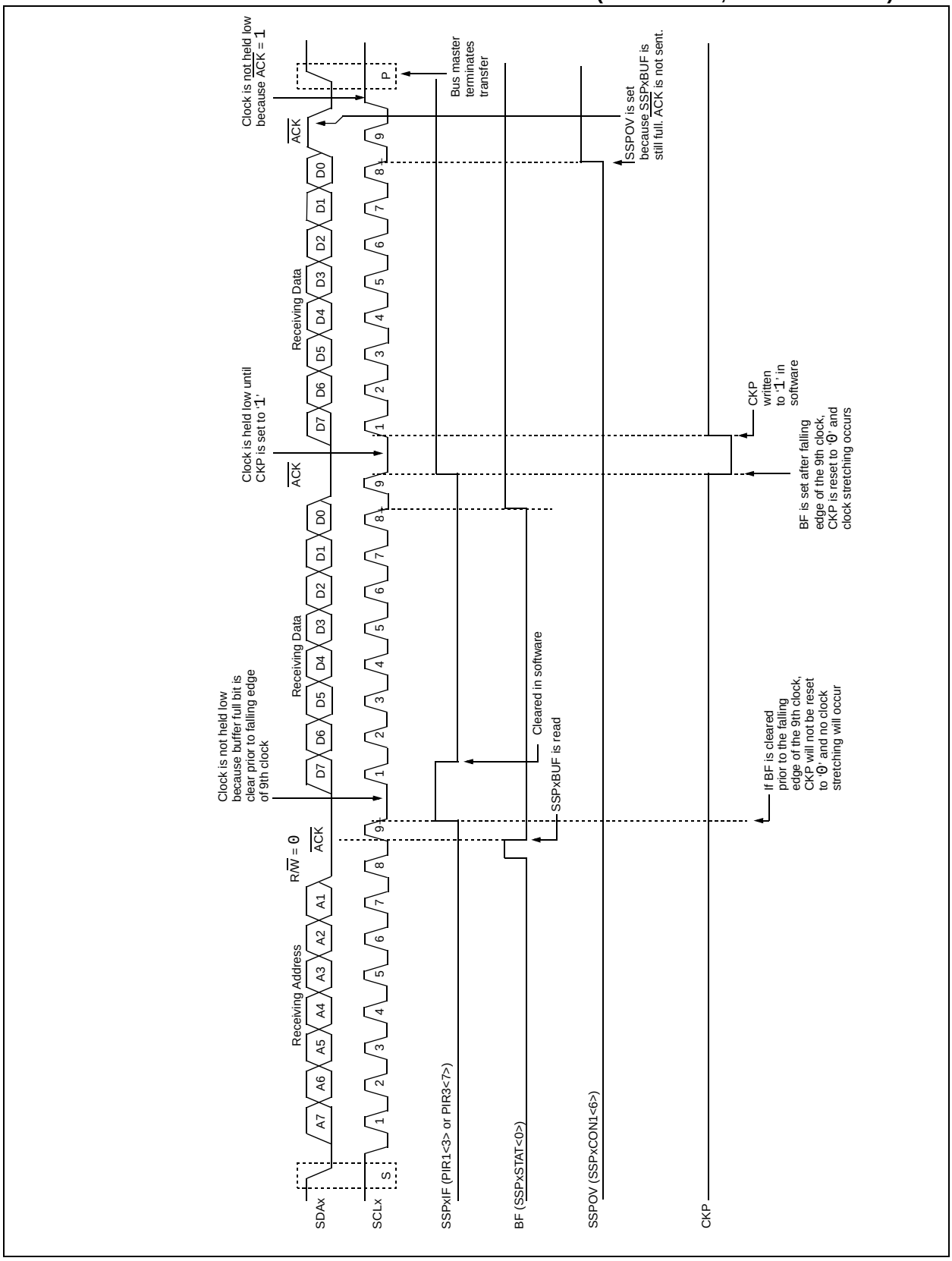


TABLE 16-1: REGISTERS ASSOCIATED WITH TIMER4 AS A TIMER/COUNTER

Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Reset Values on page
INTCON	GIE/GIEH	PEIE/GIEL	TMR0IE	INT0IE	RBIE	TMR0IF	INT0IF	RBIF	57
IPR3	SSP2IP	BCL2IP	RC2IP	TX2IP	TMR4IP	CCP5IP	CCP4IP	CCP3IP	60
PIR3	SSP2IF	BCL2IF	RC2IF	TX2IF	TMR4IF	CCP5IF	CCP4IF	CCP3IF	60
PIE3	SSP2IE	BCL2IE	RC2IE	TX2IE	TMR4IE	CCP5IE	CCP4IE	CCP3IE	60
TMR4	Timer4 Register								61
T4CON	—	T4OUTPS3	T4OUTPS2	T4OUTPS1	T4OUTPS0	TMR4ON	T4CKPS1	T4CKPS0	61
PR4	Timer4 Period Register								61

Legend: x = unknown, u = unchanged, — = unimplemented, read as '0'. Shaded cells are not used by the Timer4 module.

FIGURE 19-13: I²C™ SLAVE MODE TIMING WITH SEN = 1 (RECEPTION, 7-BIT ADDRESS)



19.4.9 I²C MASTER MODE REPEATED START CONDITION TIMING

A Repeated Start condition occurs when the RSEN bit (SSPxCON2<1>) is programmed high and the I²C logic module is in the Idle state. When the RSEN bit is set, the SCLx pin is asserted low. When the SCLx pin is sampled low, the Baud Rate Generator is loaded with the contents of SSPxADD<5:0> and begins counting. The SDAx pin is released (brought high) for one Baud Rate Generator count (TBRG). When the Baud Rate Generator times out, if SDAx is sampled high, the SCLx pin will be deasserted (brought high). When SCLx is sampled high, the Baud Rate Generator is reloaded with the contents of SSPxADD<6:0> and begins counting. SDAx and SCLx must be sampled high for one TBRG. This action is then followed by assertion of the SDAx pin (SDAx = 0) for one TBRG while SCLx is high. Following this, the RSEN bit (SSPxCON2<1>) will be automatically cleared and the Baud Rate Generator will not be reloaded, leaving the SDAx pin held low. As soon as a Start condition is detected on the SDAx and SCLx pins, the S bit (SSPxSTAT<3>) will be set. The SSPxIF bit will not be set until the Baud Rate Generator has timed out.

Note 1: If RSEN is programmed while any other event is in progress, it will not take effect.

2: A bus collision during the Repeated Start condition occurs if:

- SDAx is sampled low when SCLx goes from low-to-high.
- SCLx goes low before SDAx is asserted low. This may indicate that another master is attempting to transmit a data '1'.

Immediately following the SSPxIF bit getting set, the user may write the SSPxBUF with the 7-bit address in 7-bit mode or the default first address in 10-bit mode. After the first eight bits are transmitted and an ACK is received, the user may then transmit an additional eight bits of address (10-bit mode) or eight bits of data (7-bit mode).

19.4.9.1 WCOL Status Flag

If the user writes the SSPxBUF when a Repeated Start sequence is in progress, the WCOL is set and the contents of the buffer are unchanged (the write doesn't occur).

Note: Because queueing of events is not allowed, writing of the lower 5 bits of SSPxCON2 is disabled until the Repeated Start condition is complete.

FIGURE 19-20: REPEATED START CONDITION WAVEFORM

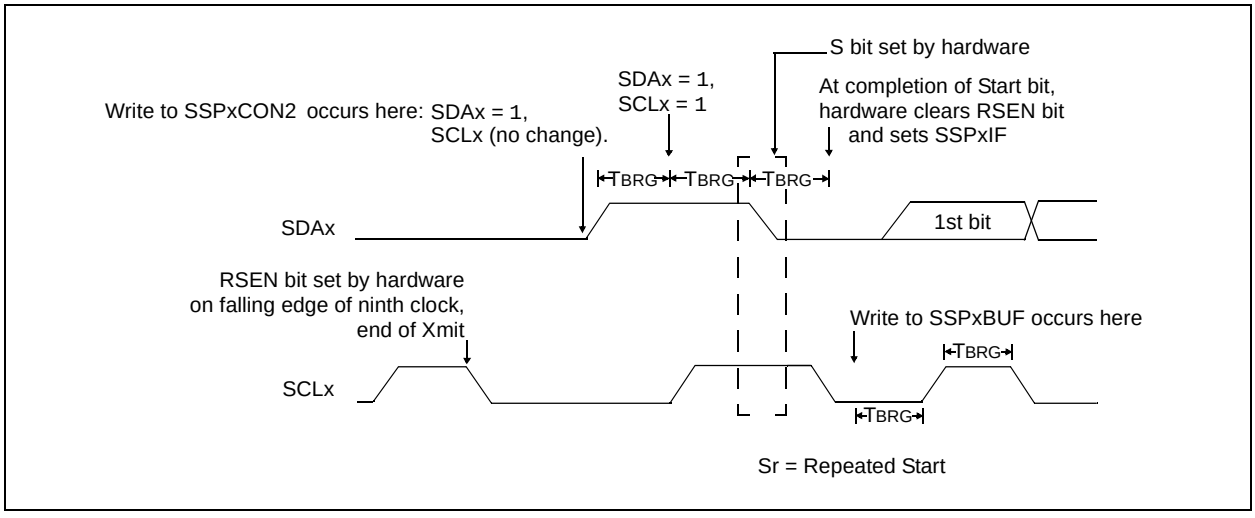
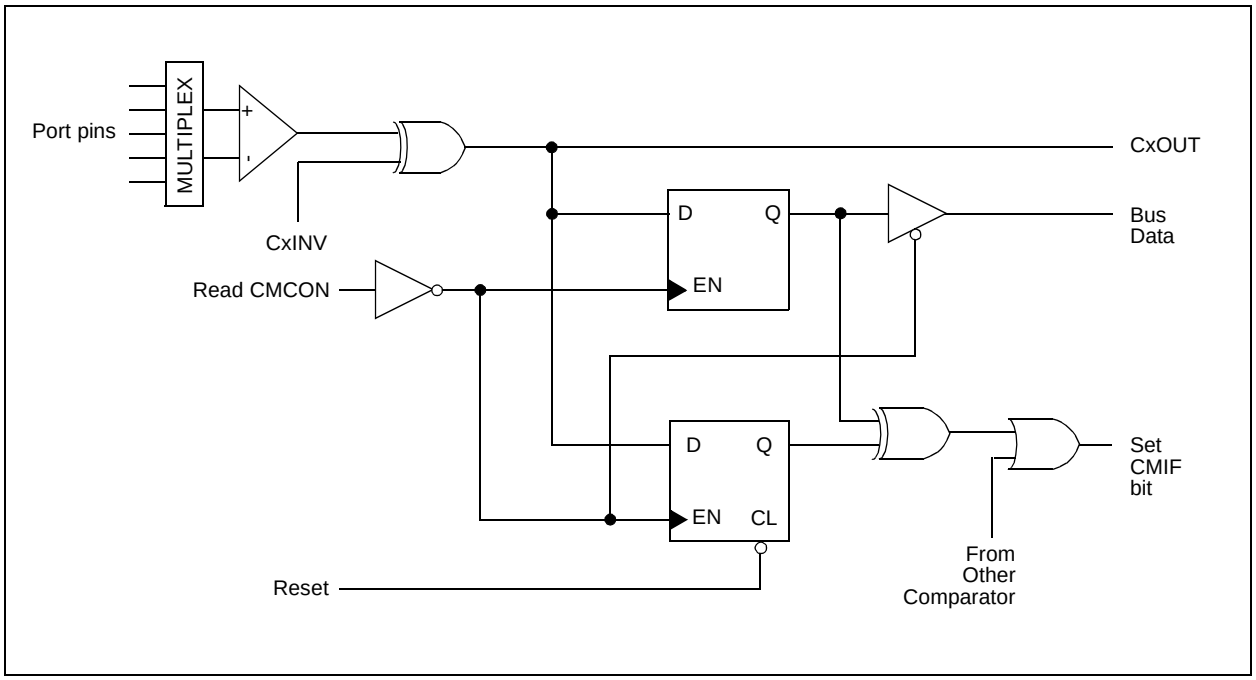


FIGURE 22-3: COMPARATOR OUTPUT BLOCK DIAGRAM



22.6 Comparator Interrupts

The comparator interrupt flag is set whenever there is a change in the output value of either comparator. Software will need to maintain information about the status of the output bits, as read from CMCON<7:6>, to determine the actual change that occurred. The CMIF bit (PIR2<6>) is the Comparator Interrupt Flag. The CMIF bit must be reset by clearing it. Since it is also possible to write a '1' to this register, a simulated interrupt may be initiated.

Both the CMIE bit (PIE2<6>) and the PEIE bit (INTCON<6>) must be set to enable the interrupt. In addition, the GIE bit (INTCON<7>) must also be set. If any of these bits are clear, the interrupt is not enabled, though the CMIF bit will still be set if an interrupt condition occurs.

Note:	If a change in the CMCON register (C1OUT or C2OUT) should occur when a read operation is being executed (start of the Q2 cycle), then the CMIF (PIR2 register) interrupt flag may not get set.

The user, in the Interrupt Service Routine, can clear the interrupt in the following manner:

a) Any read or write of CMCON will end the mismatch condition.

b) Clear flag bit, CMIF.

A mismatch condition will continue to set flag bit, CMIF. Reading CMCON will end the mismatch condition and allow flag bit, CMIF, to be cleared.

22.7 Comparator Operation During Sleep

When a comparator is active and the device is placed in Sleep mode, the comparator remains active and the interrupt is functional if enabled. This interrupt will wake-up the device from Sleep mode, when enabled. Each operational comparator will consume additional current, as shown in the comparator specifications. To minimize power consumption while in Sleep mode, turn off the comparators (CM<2:0> = 111) before entering Sleep. If the device wakes up from Sleep, the contents of the CMCON register are not affected.

22.8 Effects of a Reset

A device Reset forces the CMCON register to its Reset state, causing the comparator modules to be turned off (CM<2:0> = 111). However, the input pins (RF3 through RF6) are configured as analog inputs by default on device Reset. The I/O configuration for these pins is also determined by the setting of the PCFG<3:0> bits (ADCON1<3:0>). Therefore, device current is minimized when analog inputs are present at Reset time.

REGISTER 25-13: DEVID1: DEVICE ID REGISTER 1 FOR THE PIC18F8722 FAMILY

R	R	R	R	R	R	R	R
DEV2	DEV1	DEV0	REV4	REV3	REV2	REV1	REV0
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 7-5 **DEV<2:0>:** Device ID bits

001 = PIC18F8722
111 = PIC18F8627
101 = PIC18F8622
011 = PIC18F8527
000 = PIC18F6722
110 = PIC18F6627
100 = PIC18F6622
010 = PIC18F6527

bit 4-0 **REV<4:0>:** Revision ID bits

These bits are used to indicate the device revision.

REGISTER 25-14: DEVID2: DEVICE ID REGISTER 2 FOR THE PIC18F8722 FAMILY

R	R	R	R	R	R	R	R
DEV10(1)	DEV9(1)	DEV8(1)	DEV7(1)	DEV6(1)	DEV5(1)	DEV4(1)	DEV3(1)
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 7-0 **DEV<10:3>:** Device ID bits(1)

These bits are used with the DEV<2:0> bits in the Device ID Register 1 to identify the part number.

0001 0100 = PIC18F6722/8722 devices
0001 0011 = PIC18F6527/6622/6627/8527/8622/8627 devices

Note 1: These values for DEV<10:3> may be shared with other devices. The specific device is always identified by using the entire DEV<10:0> bit sequence.

25.5.2 DATA EEPROM CODE PROTECTION

The entire data EEPROM is protected from external reads and writes by two bits: CPD and WRTD. CPD inhibits external reads and writes of data EEPROM. WRTD inhibits internal and external writes to data EEPROM. The CPU can always read data EEPROM under normal operation, regardless of the protection bit settings.

25.5.3 CONFIGURATION REGISTER PROTECTION

The Configuration registers can be write-protected. The WRTC bit controls protection of the Configuration registers. In normal execution mode, the WRTC bit is readable only. WRTC can only be written via ICSP or an external programmer.

25.6 ID Locations

Eight memory locations (200000h-200007h) are designated as ID locations, where the user can store checksum or other code identification numbers. These locations are both readable and writable during normal execution through the TBLRD and TBLWT instructions or during program/verify. The ID locations can be read when the device is code-protected.

25.7 In-Circuit Serial Programming

The PIC18F8722 family of devices can be serially programmed while in the end application circuit. This is simply done with two lines for clock and data and three other lines for power, ground and the programming voltage. This allows customers to manufacture boards with unprogrammed devices and then program the microcontroller just before shipping the product. This also allows the most recent firmware or a custom firmware to be programmed.

25.8 In-Circuit Debugger

When the $\overline{\text{DEBUG}}$ Configuration bit is programmed to a '0', the In-Circuit Debugger functionality is enabled. This function allows simple debugging functions when used with MPLAB® IDE. When the microcontroller has this feature enabled, some resources are not available for general use. Table 25-4 shows which resources are required by the background debugger.

TABLE 25-4: DEBUGGER RESOURCES

I/O pins:	RB6, RB7
Stack:	2 levels
Program Memory:	512 bytes
Data Memory:	10 bytes

To use the In-Circuit Debugger function of the microcontroller, the design must implement In-Circuit Serial Programming connections to RG5/$\overline{\text{MCLR}}$/VPP, VDD, VSS, RB7 and RB6. This will interface to the In-Circuit Debugger module available from Microchip or one of the third party development tool companies.

25.9 Single-Supply ICSP Programming

The LVP Configuration bit enables Single-Supply ICSP Programming (formerly known as Low-Voltage ICSP Programming or LVP). When Single-Supply Programming is enabled, the microcontroller can be programmed without requiring high voltage being applied to the RG5/$\overline{\text{MCLR}}$/VPP pin, but the RB5/KBI1/PGM pin is then dedicated to controlling Program mode entry and is not available as a general purpose I/O pin.

While programming, using single-supply programming mode, VDD is applied to the RG5/$\overline{\text{MCLR}}$/VPP pin as in normal execution mode. To enter Programming mode, VDD is applied to the PGM pin.

Note 1: High-voltage programming is always available, regardless of the state of the LVP bit or the PGM pin, by applying VIHH to the $\overline{\text{MCLR}}$ pin.

2: By default, Single-Supply ICSP is enabled in unprogrammed devices (as supplied from Microchip) and erased devices.

3: When Single-Supply Programming is enabled, the RB5 pin can no longer be used as a general purpose I/O pin.

4: When LVP is enabled, externally pull the PGM pin to VSS to allow normal program execution.

If Single-Supply ICSP Programming mode will not be used, the LVP bit can be cleared. RB5/KBI1/PGM then becomes available as the digital I/O pin, RB5. The LVP bit may be set or cleared only when using standard high-voltage programming (VIHH applied to the RG5/$\overline{\text{MCLR}}$/VPP pin). Once LVP has been disabled, only the standard high-voltage programming is available and must be used to program the device.

Memory that is not code-protected can be erased using a block erase, or erased row by row, then written at any specified VDD. If code-protected memory is to be erased, a block erase is required. If a block erase is to be performed when using Low-Voltage Programming, the device must be supplied with VDD of 4.5V to 5.5V.

POP **Pop Top of Return Stack**

Syntax: POP

Operands: None

Operation: (TOS) → bit bucket

Status Affected: None

Encoding:

0000	0000	0000	0110

Description: The TOS value is pulled off the return stack and is discarded. The TOS value then becomes the previous value that was pushed onto the return stack. This instruction is provided to enable the user to properly manage the return stack to incorporate a software stack.

Words: 1

Cycles: 1

Q Cycle Activity:

Q1	Q2	Q3	Q4
Decode	No operation	POP TOS value	No operation

Example:

```
POP
GOTO    NEW
```

Before Instruction
TOS = 0031A2h
Stack (1 level down) = 014332h

After Instruction
TOS = 014332h
PC = NEW

PUSH **Push Top of Return Stack**

Syntax: PUSH

Operands: None

Operation: (PC + 2) → TOS

Status Affected: None

Encoding:

0000	0000	0000	0101

Description: The PC + 2 is pushed onto the top of the return stack. The previous TOS value is pushed down on the stack. This instruction allows implementing a software stack by modifying TOS and then pushing it onto the return stack.

Words: 1

Cycles: 1

Q Cycle Activity:

Q1	Q2	Q3	Q4
Decode	PUSH PC + 2 onto return stack	No operation	No operation

Example:

```
PUSH
```

Before Instruction
TOS = 345Ah
PC = 0124h

After Instruction
PC = 0126h
TOS = 0126h
Stack (1 level down) = 345Ah

SUBWFB **Subtract W from f with Borrow**

Syntax: SUBWFB f {,d {,a}}

Operands: $0 \le f \le 255$
$d \in [0,1]$
$a \in [0,1]$

Operation: (f) – (W) – ($\overline{C}$) → dest

Status Affected: N, OV, C, DC, Z

Encoding:

0101	10da	ffff	ffff

Description: Subtract W and the Carry flag (borrow) from register 'f' (2's complement method). If 'd' is '0', the result is stored in W. If 'd' is '1', the result is stored back in register 'f' (default).

If 'a' is '0', the Access Bank is selected. If 'a' is '1', the BSR is used to select the GPR bank (default).

If 'a' is '0' and the extended instruction set is enabled, this instruction operates in Indexed Literal Offset Addressing mode whenever f ≤ 95 (5Fh). See **Section 26.2.3 "Byte-Oriented and Bit-Oriented Instructions in Indexed Literal Offset Mode"** for details.

Words: 1

Cycles: 1

Q Cycle Activity:

Q1	Q2	Q3	Q4
Decode	Read register 'f'	Process Data	Write to destination

Example 1: `SUBWFB REG, 1, 0`

```
Before Instruction
    REG  =  19h     (0001 1001)
    W    =  0Dh     (0000 1101)
    C    =  1
After Instruction
    REG  =  0Ch     (0000 1011)
    W    =  0Dh     (0000 1101)
    C    =  1
    Z    =  0
    N    =  0       ; result is positive
```

Example 2: `SUBWFB REG, 0, 0`

```
Before Instruction
    REG  =  1Bh     (0001 1011)
    W    =  1Ah     (0001 1010)
    C    =  0
After Instruction
    REG  =  1Bh     (0001 1011)
    W    =  00h
    C    =  1
    Z    =  1       ; result is zero
    N    =  0
```

Example 3: `SUBWFB REG, 1, 0`

```
Before Instruction
    REG  =  03h     (0000 0011)
    W    =  0Eh     (0000 1101)
    C    =  1
After Instruction
    REG  =  F5h     (1111 0100)
                    ; [2's comp]
    W    =  0Eh     (0000 1101)
    C    =  0
    Z    =  0
    N    =  1       ; result is negative
```

SWAPF **Swap f**

Syntax: SWAPF f {,d {,a}}

Operands: $0 \le f \le 255$
$d \in [0,1]$
$a \in [0,1]$

Operation: (f<3:0>) → dest<7:4>,
(f<7:4>) → dest<3:0>

Status Affected: None

Encoding:

0011	10da	ffff	ffff

Description: The upper and lower nibbles of register 'f' are exchanged. If 'd' is '0', the result is placed in W. If 'd' is '1', the result is placed in register 'f' (default).

If 'a' is '0', the Access Bank is selected. If 'a' is '1', the BSR is used to select the GPR bank (default).

If 'a' is '0' and the extended instruction set is enabled, this instruction operates in Indexed Literal Offset Addressing mode whenever f ≤ 95 (5Fh). See **Section 26.2.3 "Byte-Oriented and Bit-Oriented Instructions in Indexed Literal Offset Mode"** for details.

Words: 1

Cycles: 1

Q Cycle Activity:

Q1	Q2	Q3	Q4
Decode	Read register 'f'	Process Data	Write to destination

Example: `SWAPF REG, 1, 0`

```
Before Instruction
    REG  =  53h
After Instruction
    REG  =  35h
```

27.11 PICSTART® Plus Development Programmer

The PICSTART® Plus Development Programmer is an easy-to-use, low-cost, prototype programmer. It connects to the PC via a COM (RS-232) port. MPLAB Integrated Development Environment software makes using the programmer simple and efficient. The PICSTART Plus Development Programmer supports most PIC devices in DIP packages up to 40 pins. Larger pin count devices, such as the PIC16C92X and PIC17C76X, may be supported with an adapter socket. The PICSTART Plus Development Programmer is CE compliant.

27.12 PICkit™ 2 Development Programmer

The PICkit™ 2 Development Programmer is a low-cost programmer and selected Flash device debugger with an easy-to-use interface for programming many of Microchip's baseline, mid-range and PIC18F families of Flash memory microcontrollers. The PICkit 2 Starter Kit includes a prototyping development board, twelve sequential lessons, software and HI-TECH's PICC™ Lite C compiler, and is designed to help get up to speed quickly using PIC® microcontrollers. The kit provides everything needed to program, evaluate and develop applications using Microchip's powerful, mid-range Flash memory family of microcontrollers.

27.13 Demonstration, Development and Evaluation Boards

A wide variety of demonstration, development and evaluation boards for various PIC MCUs and dsPIC DSCs allows quick application development on fully functional systems. Most boards include prototyping areas for adding custom circuitry and provide application firmware and source code for examination and modification.

The boards support a variety of features, including LEDs, temperature sensors, switches, speakers, RS-232 interfaces, LCD displays, potentiometers and additional EEPROM memory.

The demonstration and development boards can be used in teaching environments, for prototyping custom circuits and for learning about various microcontroller applications.

In addition to the PICDEM™ and dsPICDEM™ demonstration/development board series of circuits, Microchip has a line of evaluation kits and demonstration software for analog filter design, KEELOQ® security ICs, CAN, IrDA®, PowerSmart battery management, SEEVAL® evaluation system, Sigma-Delta ADC, flow rate sensing, plus many more.

Check the Microchip web page (www.microchip.com) for the complete list of demonstration, development and evaluation kits.

28.0 ELECTRICAL CHARACTERISTICS

Absolute Maximum Ratings(†)

Ambient temperature under bias ..... -40°C to +125°C
Storage temperature ..... -65°C to +150°C
Voltage on any pin with respect to V_{SS} (except V_{DD} and $\overline{MCLR}$) ..... -0.3V to (V_{DD} + 0.3V)
Voltage on V_{DD} with respect to V_{SS} ..... -0.3V to +7.5V
Voltage on $\overline{MCLR}$ with respect to V_{SS} **(Note 2)** ..... 0V to +13.25V
Total power dissipation **(Note 1)** 1.0W
Maximum current out of V_{SS} pin ..... 300 mA
Maximum current into V_{DD} pin ..... 250 mA
Input clamp current, I_{IK} (V_I < 0 or V_I > V_{DD}) ..... ±20 mA
Output clamp current, I_{OK} (V_O < 0 or V_O > V_{DD}) ..... ±20 mA
Maximum output current sunk by any I/O pin ..... 25 mA
Maximum output current sourced by any I/O pin ..... 25 mA
Maximum current sunk by all ports ..... 200 mA
Maximum current sourced by all ports ..... 200 mA

Note 1: Power dissipation is calculated as follows:
$P_{dis} = V_{DD} \times \{I_{DD} - \sum I_{OH}\} + \sum \{(V_{DD} - V_{OH}) \times I_{OH}\} + \sum (V_{OL} \times I_{OL})$

2: Voltage spikes below V_{SS} at the RG5/$\overline{MCLR}$/V_{PP} pin, inducing currents greater than 80 mA, may cause latch-up. Thus, a series resistor of 50-100Ω should be used when applying a “low” level to the RG5/$\overline{MCLR}$/V_{PP} pin, rather than pulling this pin directly to V_{SS}.

† **NOTICE:** Stresses above those listed under “Absolute Maximum Ratings” may cause permanent damage to the device. This is a stress rating only and functional operation of the device at those or any other conditions above those indicated in the operation listings of this specification is not implied. Exposure to maximum rating conditions for extended periods may affect device reliability.

TABLE 28-7: PLL CLOCK TIMING SPECIFICATIONS (V_{DD} = 4.2V TO 5.5V)

Param No.	Sym	Characteristic	Min	Typ†	Max	Units	Conditions
F10	FOSC	Oscillator Frequency Range	4	—	10	MHz	HS mode only
F11	FSYS	On-Chip VCO System Frequency	16	—	40	MHz	HS mode only
F12	t_{rc}	PLL Start-up Time (Lock Time)	—	—	2	ms	
F13	ΔCLK	CLKO Stability (Jitter)	-2	—	+2	%	

† Data in "Typ" column is at 5V, 25°C, unless otherwise stated. These parameters are for design guidance only and are not tested.

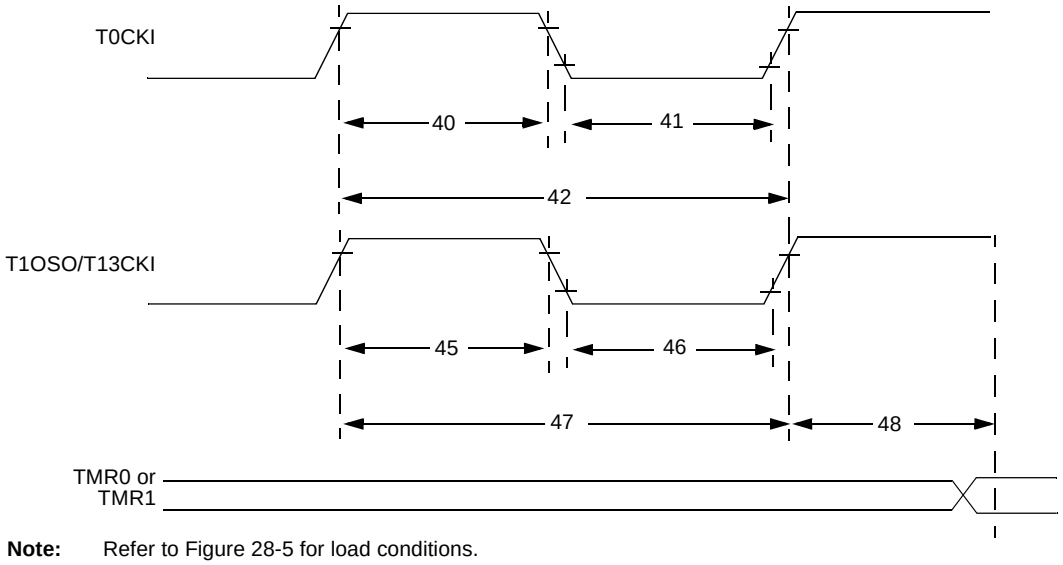
TABLE 28-8: AC CHARACTERISTICS: INTERNAL RC ACCURACY PIC18F6X27/6X22/8X27/8X22 (INDUSTRIAL, EXTENDED) PIC18LF6X27/6X22/8X27/8X22 (INDUSTRIAL)

PIC18LF6X27/6X22/8X27/8X22 (Industrial)		**Standard Operating Conditions (unless otherwise stated)** Operating temperature -40°C ≤ TA ≤ +85°C for industrial					
PIC18F6X27/6X22/8X27/8X22 (Industrial, Extended)		**Standard Operating Conditions (unless otherwise stated)** Operating temperature -40°C ≤ TA ≤ +85°C for industrial -40°C ≤ TA ≤ +125°C for extended					
Param No.	**Device**	**Min**	**Typ**	**Max**	**Units**	**Conditions**	
	INTOSC Accuracy @ Freq = 8 MHz, 4 MHz, 2 MHz, 1 MHz, 500 kHz, 250 kHz, 125 kHz(1)						
	PIC18LF6X27/6X22/8X27/8X22	-2	+/-1	2	%	+25°C	VDD = 2.7-3.3V
		-5	+/-1	5	%	-40°C to +85°C	VDD = 2.7-3.3V
	PIC18F6X27/6X22/8X27/8X22	-2	+/-1	2	%	+25°C	VDD = 4.5-5.5V
		-5	+/-1	5	%	-40°C to +85°C	VDD = 4.5-5.5V
	INTRC Accuracy @ Freq = 31 kHz						
	PIC18LF6X27/6X22/8X27/8X22	26.562	—	35.938	kHz	-40°C to +85°C	VDD = 2.7-3.3V
	PIC18F6X27/6X22/8X27/8X22	26.562	+/-8	35.938	kHz	-40°C to +85°C	VDD = 4.5-5.5V

Legend: Shading of rows is to assist in readability of the table.

Note 1: Frequency calibrated at 25°C. OSCTUNE register can be used to compensate for temperature drift.

FIGURE 28-12: TIMER0 AND TIMER1 EXTERNAL CLOCK TIMINGS



Note: Refer to Figure 28-5 for load conditions.

TABLE 28-13: TIMER0 AND TIMER1 EXTERNAL CLOCK REQUIREMENTS

Param No.	Symbol	Characteristic			Min	Max	Units	Conditions
40	TT0H	T0CKI High Pulse Width		No prescaler	0.5 TCY + 20	—	ns	
				With prescaler	10	—	ns	
41	TT0L	T0CKI Low Pulse Width		No prescaler	0.5 TCY + 20	—	ns	
				With prescaler	10	—	ns	
42	TT0P	T0CKI Period		No prescaler	TCY + 10	—	ns	
				With prescaler	Greater of: 20 ns or (TCY + 40)/N	—	ns	N = prescale value (1, 2, 4,..., 256)
45	TT1H	T13CKI High Time	Synchronous, no prescaler		0.5 TCY + 20	—	ns	
			Synchronous, with prescaler	PIC18**F**XXXX	10	—	ns	
				PIC18**LF**XXXX	25	—	ns	VDD = 2.0V
			Asynchronous	PIC18**F**XXXX	30	—	ns	
				PIC18**LF**XXXX	50	—	ns	VDD = 2.0V
46	TT1L	T13CKI Low Time	Synchronous, no prescaler		0.5 TCY + 5	—	ns	
			Synchronous, with prescaler	PIC18**F**XXXX	10	—	ns	
				PIC18**LF**XXXX	25	—	ns	VDD = 2.0V
			Asynchronous	PIC18**F**XXXX	30	—	ns	
				PIC18**LF**XXXX	50	—	ns	VDD = 2.0V
47	TT1P	T13CKI Input Period	Synchronous		Greater of: 20 ns or (TCY + 40)/N	—	ns	N = prescale value (1, 2, 4, 8)
			Asynchronous		60	—	ns	
	FT1	T13CKI Oscillator Input Frequency Range			DC	50	kHz	
48	TCKE2TMRI	Delay from External T13CKI Clock Edge to Timer Increment			2 TOSC	7 TOSC	—	

TABLE 28-23: MASTER SSP I²C™ BUS DATA REQUIREMENTS

Param. No.	Symbol	Characteristic		Min	Max	Units	Conditions
100	THIGH	Clock High Time	100 kHz mode	2(TOSC)(BRG + 1)	—	ms	
			400 kHz mode	2(TOSC)(BRG + 1)	—	ms	
			1 MHz mode(1)	2(TOSC)(BRG + 1)	—	ms	
101	TLOW	Clock Low Time	100 kHz mode	2(TOSC)(BRG + 1)	—	ms	
			400 kHz mode	2(TOSC)(BRG + 1)	—	ms	
			1 MHz mode(1)	2(TOSC)(BRG + 1)	—	ms	
102	TR	SDAx and SCLx Rise Time	100 kHz mode	—	1000	ns	CB is specified to be from 10 to 400 pF
			400 kHz mode	20 + 0.1 CB	300	ns	
			1 MHz mode(1)	—	300	ns	
103	TF	SDAx and SCLx Fall Time	100 kHz mode	—	300	ns	CB is specified to be from 10 to 400 pF
			400 kHz mode	20 + 0.1 CB	300	ns	
			1 MHz mode(1)	—	100	ns	
90	TSU:STA	Start Condition Setup Time	100 kHz mode	2(TOSC)(BRG + 1)	—	ms	Only relevant for Repeated Start condition
			400 kHz mode	2(TOSC)(BRG + 1)	—	ms	
			1 MHz mode(1)	2(TOSC)(BRG + 1)	—	ms	
91	THD:STA	Start Condition Hold Time	100 kHz mode	2(TOSC)(BRG + 1)	—	ms	After this period, the first clock pulse is generated
			400 kHz mode	2(TOSC)(BRG + 1)	—	ms	
			1 MHz mode(1)	2(TOSC)(BRG + 1)	—	ms	
106	THD:DAT	Data Input Hold Time	100 kHz mode	0	—	ns	
			400 kHz mode	0	0.9	ms	
			1 MHz mode(1)	TBD	—	ns	
107	TSU:DAT	Data Input Setup Time	100 kHz mode	250	—	ns	**(Note 2)**
			400 kHz mode	100	—	ns	
			1 MHz mode(1)	TBD	—	ns	
92	TSU:STO	Stop Condition Setup Time	100 kHz mode	2(TOSC)(BRG + 1)	—	ms	
			400 kHz mode	2(TOSC)(BRG + 1)	—	ms	
			1 MHz mode(1)	2(TOSC)(BRG + 1)	—	ms	
109	TAA	Output Valid from Clock	100 kHz mode	—	3500	ns	
			400 kHz mode	—	1000	ns	
			1 MHz mode(1)	—	—	ns	
110	TBUF	Bus Free Time	100 kHz mode	4.7	—	ms	Time the bus must be free before a new transmission can start
			400 kHz mode	1.3	—	ms	
			1 MHz mode(1)	TBD	—	ms	
D102	CB	Bus Capacitive Loading		—	400	pF	

Legend: TBD = To Be Determined

Note 1: Maximum pin capacitance = 10 pF for all I²C™ pins.

2: A Fast mode I²C bus device can be used in a Standard mode I²C bus system, but parameter #107 ≥ 250 ns must then be met. This will automatically be the case if the device does not stretch the LOW period of the SCLx signal. If such a device does stretch the LOW period of the SCLx signal, it must output the next data bit to the SDAx line, parameter #102 + parameter #107 = 1000 + 250 = 1250 ns (for 100 kHz mode,) before the SCLx line is released.

NOTES: